

RF Chip Attenuators

Flip Chip and Die Mount

9552 Series

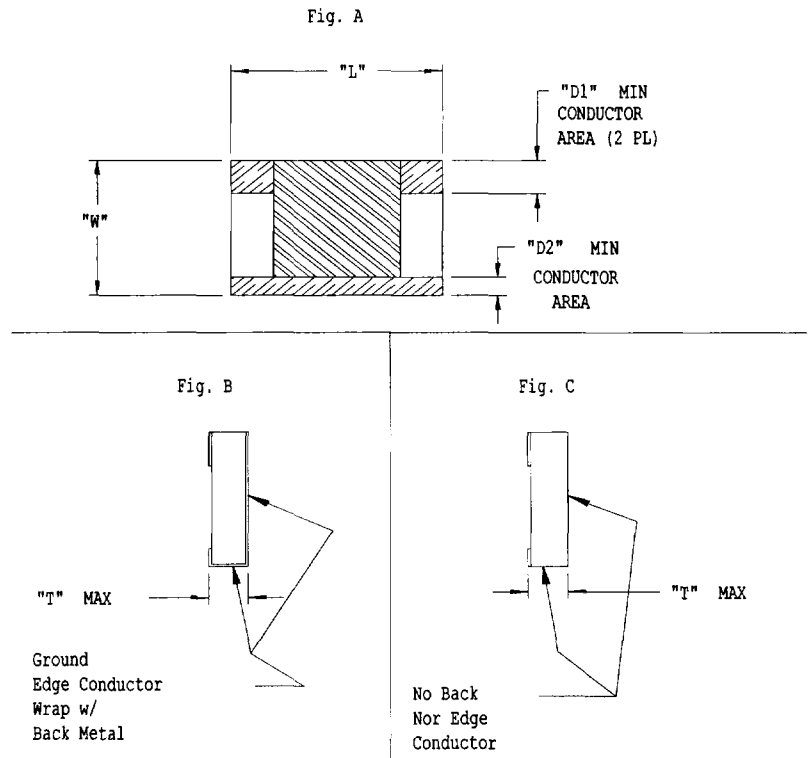
V2.00

Features

- 99.6% Aluminum Oxide Ceramic
- Available with Gold or Solder Tinned Conductors
- Available with/without Ground Wrap / Back Metal
- Additional Configurations available.

Description

A Chip Attenuator designed for use in Microstrip or Stripline applications to reduce and balance power outputs between stages of systems. These are designed to be used as either a Flip Chip directly mounted by D1 on a line with a ground provided at D2 or mounted to a Ground Pad and strapped or wire bonded input/output to D1 I/O. Chips with Back Metal may be mounted using solder, conductive epoxies, eutectics, and similar methods. Solder tinned units utilize SN 63 for solder reflow.



Ordering Information

PART NUMBER (-XX = 01 TO -20) dB	Fig(s).	L ± .002	W ± .002	T ± .0015	D1	D2	WIRE BONDABLE	SOLDER TINNED	GROUND WRAP	BACKSIDE METAL
9552-6008-XX	A & B	.075	.060	.010	.010	.005	YES	NO	YES	YES
9552-6012-XX	A & C	.075	.060	.010	.010	.005	YES	NO	NO	NO
9552-6019-XX	A & B	.075	.060	.010	.010	.005	NO	YES	YES	YES
9552-6023-XX	A & C	.075	.060	.010	.010	.005	NO	YES	NO	NO
9552-6006-XX	A & B	.148	.120	.010	.010	.005	YES	NO	YES	YES
9552-6010-XX	A & C	.148	.120	.010	.010	.005	YES	NO	NO	NO
9552-6017-XX	A & B	.148	.120	.010	.010	.005	NO	YES	YES	YES
9552-6021-XX	A & C	.148	.120	.010	.010	.005	NO	YES	NO	NO
9552-6007-XX	A & B	.148	.120	.025	.020	.008	YES	NO	YES	YES
9552-6011-XX	A & C	.148	.120	.025	.020	.008	YES	NO	NO	NO
9552-6018-XX	A & B	.148	.120	.025	.020	.008	NO	YES	YES	YES
9552-6022-XX	A & C	.148	.120	.025	.020	.008	NO	YES	NO	NO